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We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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3.0mmx1.0 mm RIGHT ANGLE SMD **CHIP LED LAMP**

Part Number: APA3010CGCK-GX Green

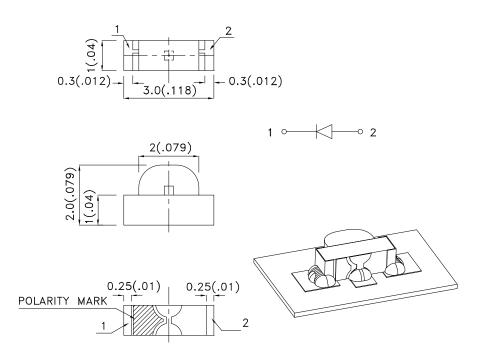
Features

- 3.0mmx1.0mm right angle SMT LED, 2.0mm thickness.
- Low power consumption.
- Wide viewing angle.
- Ideal for back light and indicator.
- Various colors and lens types available.
- Package: 2000pcs / reel.
- Moisture sensitivity level : level 3.
- Tinned pads for improved solderability.
- RoHS compliant.

Description

The Green source color devices are made with AlGaInP on GaAs substrate Light Emitting Diode.

Package Dimensions



- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is ±0.15(0.006") unless otherwise noted.
- The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.
 The device has a single mounting surface. The device must be mounted according to the specifications.



SPEC NO: DSAL3671 **REV NO: V.1 DATE: NOV/11/2010** PAGE: 1 OF 5 APPROVED: WYNEC **CHECKED: Allen Liu** DRAWN: F.F.Zhou ERP: 1203000554

Selection Guide

Part No.	Dice	Lens Type	lv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Тур.	201/2
APA3010CGCK-GX	Green (AlGaInP)	Water Clear	40	60	120°

- Notes: 1. θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value. 2. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Green	574		nm	IF=20mA
λD [1]	Dominant Wavelength	Green	570		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Green	20		nm	I==20mA
С	Capacitance	Green	15		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Green	2.1	2.5	V	IF=20mA
lr	Reverse Current	Green		10	uA	V _R =5V

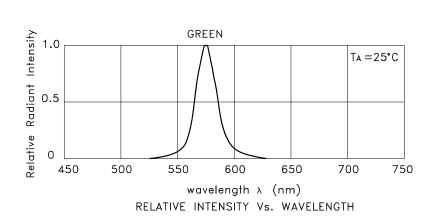
- Notes: 1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

Parameter	Green		
Power dissipation	75	mW	
DC Forward Current	30	mA	
Peak Forward Current [1]	150	mA	
Reverse Voltage	5	V	
Operating Temperature	-40°C To +85°C		
Storage Temperature	-40°C To +85°C		

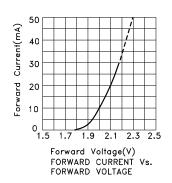
Note: 1. 1/10 Duty Cycle, 0.1ms Pulse Width.

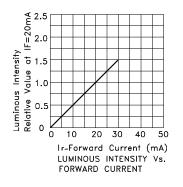
SPEC NO: DSAL3671 **REV NO: V.1 DATE: NOV/11/2010** PAGE: 2 OF 5 APPROVED: WYNEC **CHECKED: Allen Liu** DRAWN: F.F.Zhou ERP: 1203000554

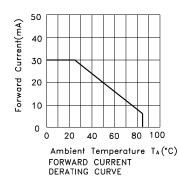


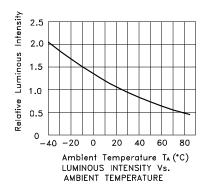
Green

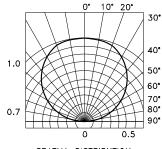
APA3010CGCK-GX











SPATIAL DISTRIBUTION

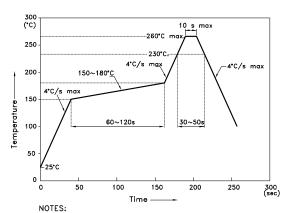
 SPEC NO: DSAL3671
 REV NO: V.1
 DATE: NOV/11/2010
 PAGE: 3 OF 5

 APPROVED: WYNEC
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APA3010CGCK-GX

Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.



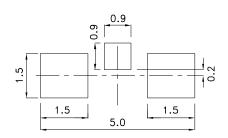
- NOTES:

 1.We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.

 2.Don't cause stress to the epoxy resin while it is exposed to high temperature.

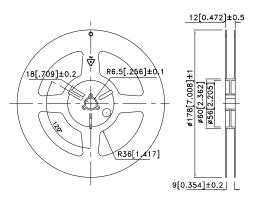
 3.Number of reflow process shall be 2 times or less.

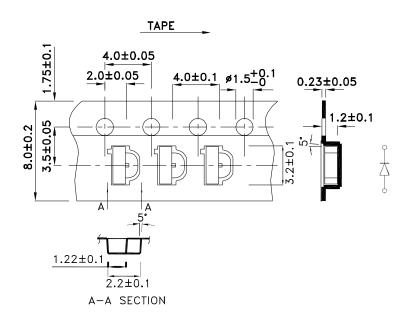
Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)



Tape Dimensions (Units: mm)

Reel Dimension

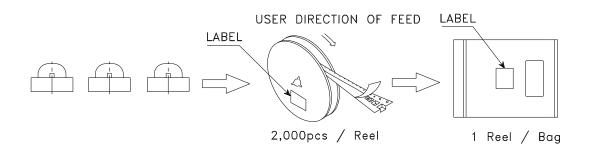


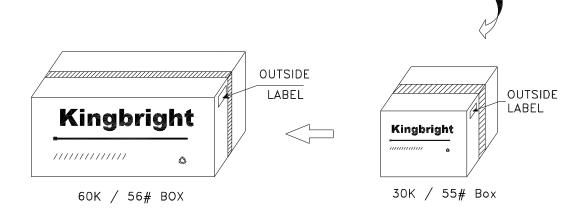


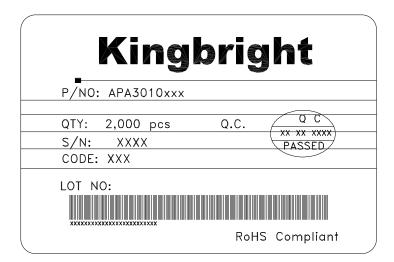
SPEC NO: DSAL3671 **REV NO: V.1 DATE: NOV/11/2010** PAGE: 4 OF 5 CHECKED: Allen Liu **APPROVED: WYNEC** DRAWN: F.F.Zhou ERP: 1203000554

PACKING & LABEL SPECIFICATIONS

APA3010CGCK-GX







SPEC NO: DSAL3671 APPROVED: WYNEC

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PAGE: 5 OF 5 ERP: 1203000554